COMPLIANT

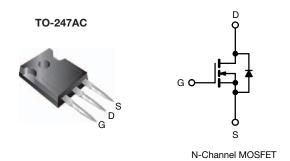
HALOGEN

FREE



## **E Series Power MOSFET**

PRODUCT SUMMARY				
V <sub>DS</sub> (V) at T <sub>J</sub> max.	650			
R <sub>DS(on)</sub> max. (Ω) at 25 °C	V <sub>GS</sub> = 10 V 0.18			
Q <sub>g</sub> max. (nC)	86			
Q <sub>gs</sub> (nC)	11			
Q <sub>gd</sub> (nC)	24			
Configuration	Single			



#### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q<sub>a</sub>)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### **APPLICATIONS**

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Industrial
  - Welding
  - Induction heating
  - Motor drives
  - Battery chargers
  - Renewable energy
  - Solar (PV inverters)

ORDERING INFORMATION				
Package	TO-247AC			
Lead (Pb)-free	SiHG22N60E-E3			
Lead (Pb)-free and Halogen-free	SiHG22N60E-GE3			

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V <sub>DS</sub>	600		
Gate-Source Voltage			$V_{GS}$	± 30	V	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	V <sub>GS</sub> at 10 V	$T_{\rm C} = 25  ^{\circ}{\rm C}$ $T_{\rm C} = 100  ^{\circ}{\rm C}$	I <sub>D</sub>	21	А	
		T <sub>C</sub> = 100 °C		13		
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	56		
Linear Derating Factor				1.8	W/°C	
Single Pulse Avalanche Energy b			E <sub>AS</sub>	367	mJ	
Maximum Power Dissipation			$P_{D}$	227	W	
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Drain-Source Voltage Slope T <sub>J</sub> = 125 °C		dV/dt	70	V/ns		
Reverse Diode dV/dt <sup>d</sup>			11	] v/fis		
Soldering Recommendations (Peak temperature) c for 10 s				300	°C	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b.  $V_{DD}$  = 50 V, starting  $T_J$  = 25 °C, L = 28.2 mH,  $R_g$  = 25  $\Omega$ ,  $I_{AS}$  = 5.1 A.
- c. 1.6 mm from case.
- d.  $I_{SD} \le I_D$ ,  $dI/dt = 100 \text{ A/}\mu\text{s}$ , starting  $T_J = 25 \,^{\circ}\text{C}$ .



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62	°C/W	
Maximum Junction-to-Case (Drain)	$R_{thJC}$	-	0.55	C/ VV	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		-					
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I <sub>D</sub> = 250 μA	=.	0.71	-	V/°C
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2	-	4	V
Cata Carriaga Lagliaga	I <sub>GSS</sub>	V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
Gate-Source Leakage			$V_{GS} = \pm 30 \text{ V}$	-		± 1	μΑ
Zava Cata Valtaga Dvain Cuwant		V <sub>DS</sub> =	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V		-	1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 480 \	/, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 11 A	-	0.15	0.18	Ω
Forward Transconductance	9 <sub>fs</sub>	V <sub>D</sub>	<sub>S</sub> = 8 V, I <sub>D</sub> = 5 A	-	6.4	-	S
Dynamic							
Input Capacitance	C <sub>iss</sub>		$V_{GS} = 0 V$ ,	-	1920	-	
Output Capacitance	C <sub>oss</sub>		$V_{DS} = 100 \text{ V},$	-	90	-	
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1 MHz		-	6	-	pF
Effective Output Capacitance, Energy Related <sup>a</sup>	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V		-	73	-	
Effective Output Capacitance, Time Related <sup>b</sup>	C <sub>o(tr)</sub>			-	263	-	
Total Gate Charge	Qg				57	86	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{GS} = 10 \text{ V}$ $I_D = 11 \text{ A}, V_{DS} = 480 \text{ V}$		-	11	-	
Gate-Drain Charge	Q <sub>gd</sub>			-	24	-	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 380 V, I <sub>D</sub> = 11 A,		-	18	36	
Rise Time	t <sub>r</sub>			-	27	54	
Turn-Off Delay Time	t <sub>d(off)</sub>		= 10 V, $R_q = 4.7 \Omega$	-	66	99	ns
Fall Time	t <sub>f</sub>				35	70	
Gate Input Resistance	$R_g$	f = 1 MHz, open drain		0.3	0.77	1.2	Ω
Drain-Source Body Diode Characteristic	s						•
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	21	_
Pulsed Diode Forward Current	I <sub>SM</sub>			-	-	56	A
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 11 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse Recovery Time	t <sub>rr</sub>			_	344	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>	$T_J = 25 \text{ °C, } I_F = I_S = 11 \text{ A,}$ $dI/dt = 100 \text{ A/}\mu\text{s, } V_R = 25 \text{ V}$		-	5.3	-	μC
Reverse Recovery Current	I <sub>RRM</sub>			-	28	-	A

#### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .
- b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

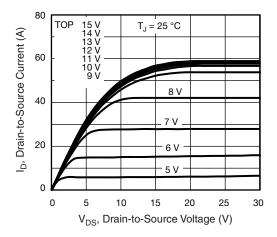


Fig. 1 - Typical Output Characteristics

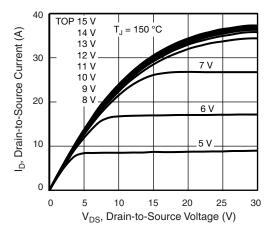


Fig. 2 - Typical Output Characteristics

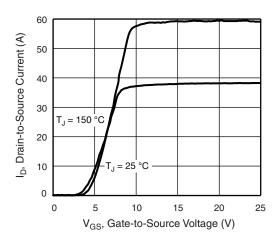


Fig. 3 - Typical Transfer Characteristics

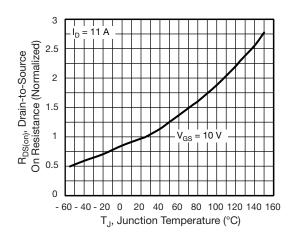


Fig. 4 - Normalized On-Resistance vs. Temperature

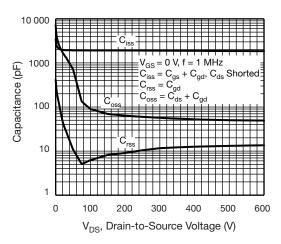


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

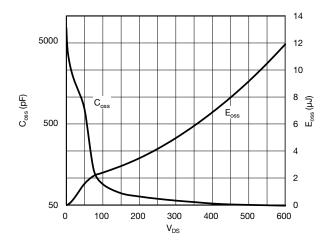


Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$ 



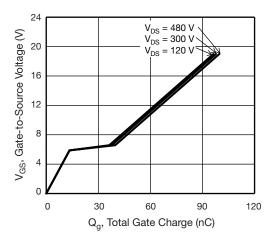


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

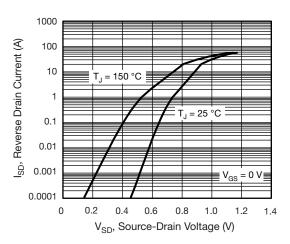


Fig. 8 - Typical Source-Drain Diode Forward Voltage

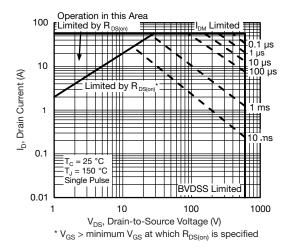


Fig. 9 - Maximum Safe Operating Area

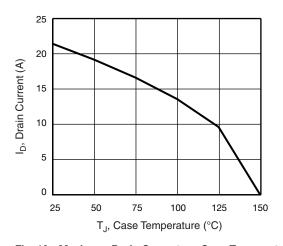


Fig. 10 - Maximum Drain Current vs. Case Temperature

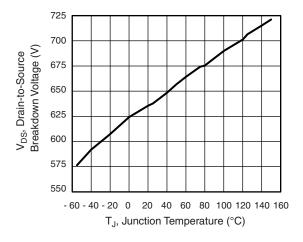


Fig. 11 - Temperature vs. Drain-to-Source Voltage



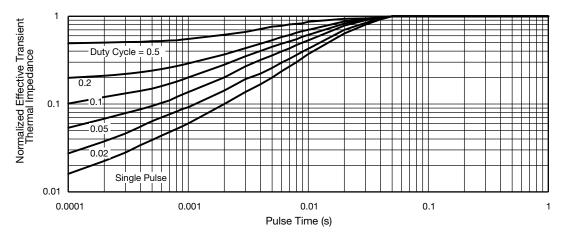


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

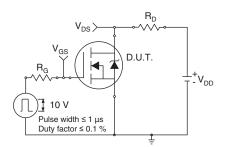


Fig. 13 - Switching Time Test Circuit

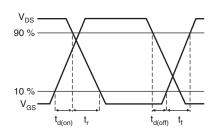


Fig. 14 - Switching Time Waveforms

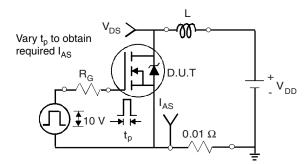


Fig. 15 - Unclamped Inductive Test Circuit

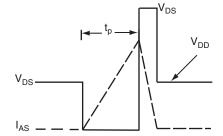


Fig. 16 - Unclamped Inductive Waveforms

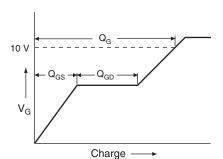


Fig. 17 - Basic Gate Charge Waveform

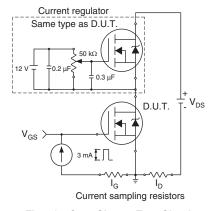
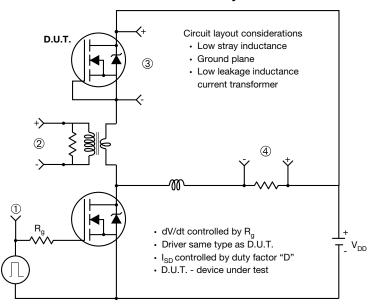


Fig. 18 - Gate Charge Test Circuit



### Peak Diode Recovery dV/dt Test Circuit



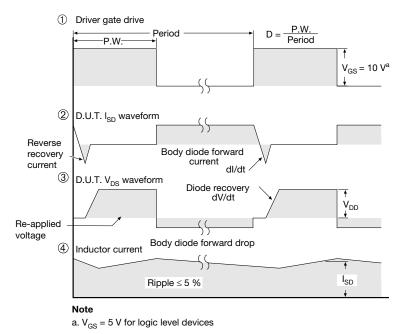
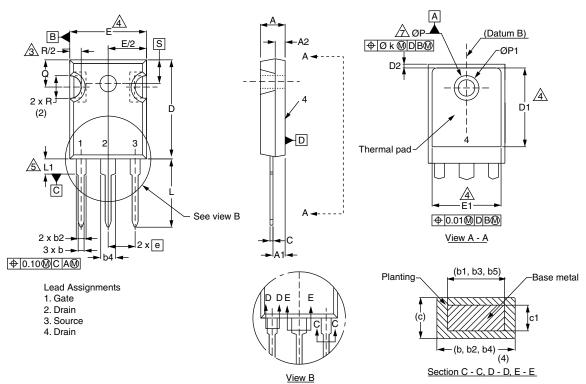


Fig. 19 - For N-Channel

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# **TO-247AC (High Voltage)**



	MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
Α	4.58	5.31	0.180	0.209
A1	2.21	2.59	0.087	0.102
A2	1.17	2.49	0.046	0.098
b	0.99	1.40	0.039	0.055
b1	0.99	1.35	0.039	0.053
b2	1.53	2.39	0.060	0.094
b3	1.65	2.37	0.065	0.093
b4	2.42	3.43	0.095	0.135
b5	2.59	3.38	0.102	0.133
С	0.38	0.86	0.015	0.034
c1	0.38	0.76	0.015	0.030
D	19.71	20.82	0.776	0.820
D1	13.08	-	0.515	-

	MILLIM	IETERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
D2	0.51	1.30	0.020	0.051	
E	15.29	15.87	0.602	0.625	
E1	13.72	ı	0.540	ı	
е	5.46	BSC	0.215 BSC		
Øk	0.2	0.254		0.010	
L	14.20	16.25	0.559	0.640	
L1	3.71	4.29	0.146	0.169	
N	7.62 BSC		0.300 BSC		
ØΡ	3.51	3.66	0.138	0.144	
Ø P1	-	7.39	-	0.291	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	0.178	0.216	
S	5.51 BSC		0.217 BSC		
0.217 800					

ECN: X13-0103-Rev. D, 01-Jul-13

DWG: 5971

#### **Notes**

- 1. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 2. Contour of slot optional.
- 3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body.
- 4. Thermal pad contour optional with dimensions D1 and E1.
  5. Lead finish uncontrolled in L1.
- 6. Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154").
- 7. Outline conforms to JEDEC outline TO-247 with exception of dimension c.
- 8. Xian and Mingxin actually photo.





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